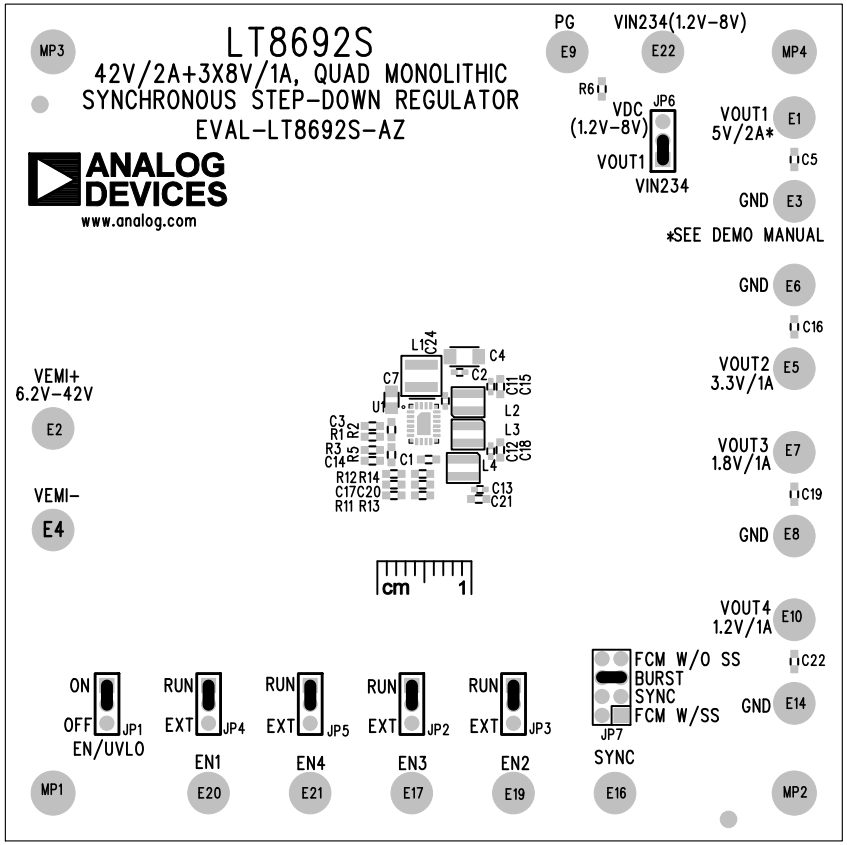
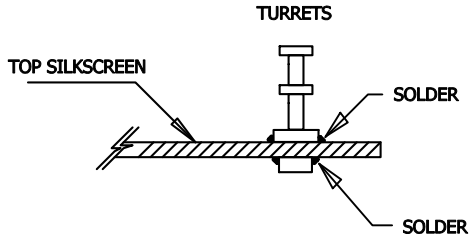


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 deg C.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNT AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.



ANALOG DEVICES
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TITLE: TOP ASSEMBLY DRAWING
42V/2A+3X8V/1A, QUAD MONOLITHIC
SYNCHRONOUS STEP-DOWN REGULATOR

SIZE	IC NO.	REV.
N/A	LT8692SEV EVAL-LT8692S-AZ	4

FILENAME: EVAL-LT8692S-AZ-4.PCB | SHT 1 OF 2